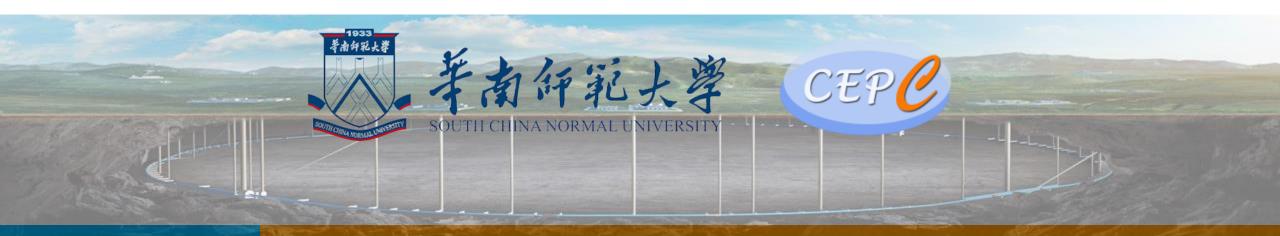
2025 European Edition of the International Workshop on the Circular Electron-Positron Collider (CEPC), Barcelona, Spain

■ 16 Jun 2025, 08:00 → 19 Jun 2025, 14:10 UTC

Status of the CEPC GS-HCAL

Hengne Li (SCNU) on behalf of the CEPC HCAL Group



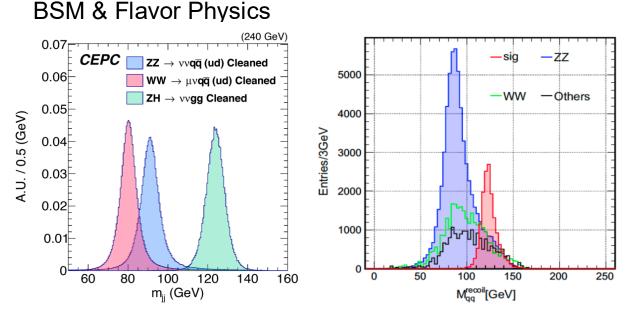
Physics Requirements of HCAL

CEPC HCAL Design requirements:

*****Jet Energy Resolution $\Delta E/E < 30\%/\sqrt{E}$ GeV

♦ Boson Mass Resolution (BMR) < 4% :

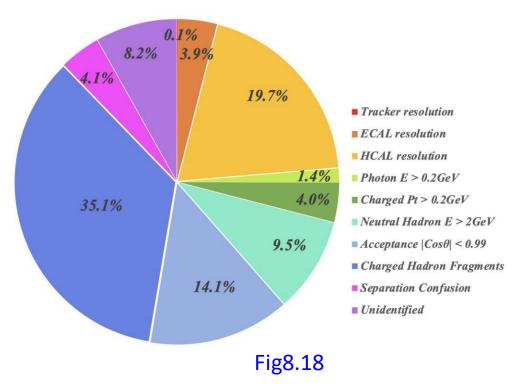
it is strongly motivated by H/W/Z hadronic final states,



CDR baseline (*arXiv:1811.10545*): BMR = 3.75%

Leading contributions to BMR:

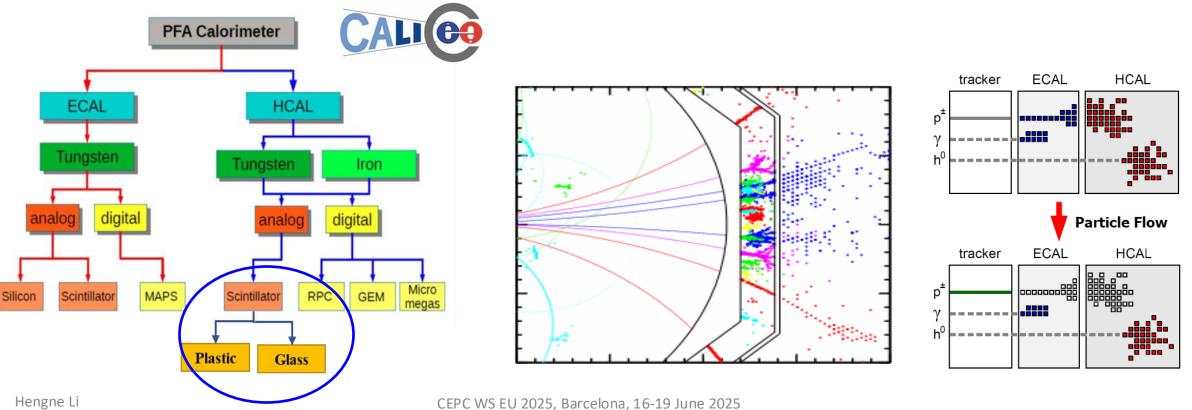
- HCAL resolution dominant the uncertainties from intrinsic detector resolution: ~19.7%
- Further improvement of HCAL is needed



Technology Survey

PFA calorimetry: extensively explored within the CALICE collab.

- RPC-DHCAL (SDHCAL): 48-layer prototype
- Plastic Scintillator-AHCAL (PS-HCAL): 40-layer prototype
- Glass Scintillator-AHCAL (GS-HCAL): new design and baseline

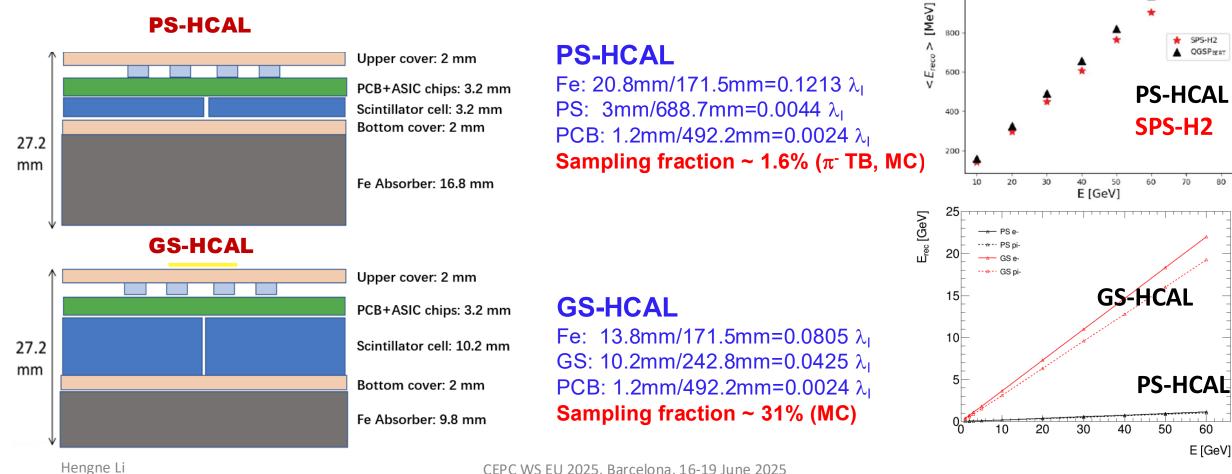


3

Glass Scintillator HCAL

- **Basic idea:** to increase sampling fraction for better energy resolution
- With high density and thick GS cell design, the sampling fraction of GS-HCAL can be increased by a factor of ~20 compared to that of PS-HCAL

PS-HCAL



60

SPS-H2

QGSPBERT

CEPC AHCAL

Pion beam

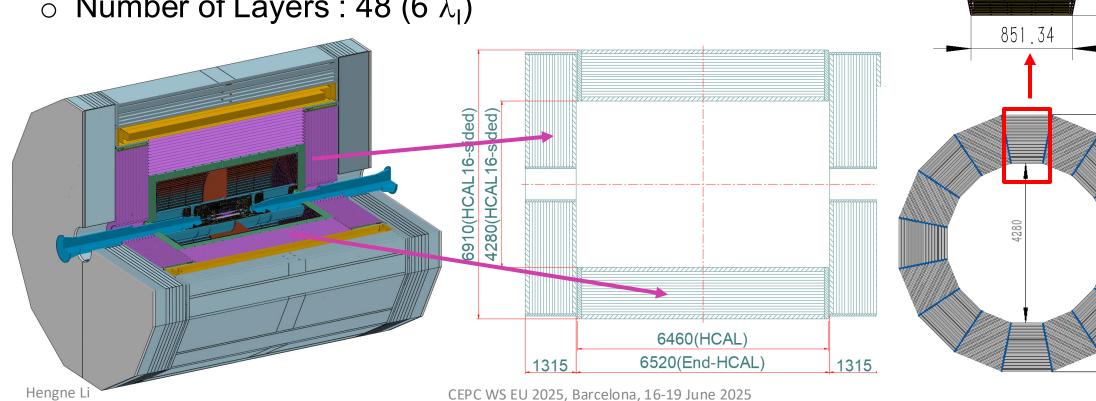
1200

1000

GS-HCAL Mechanical Design

□ GS-HCAL: One Barrel (16 wedges) and Two Endcaps

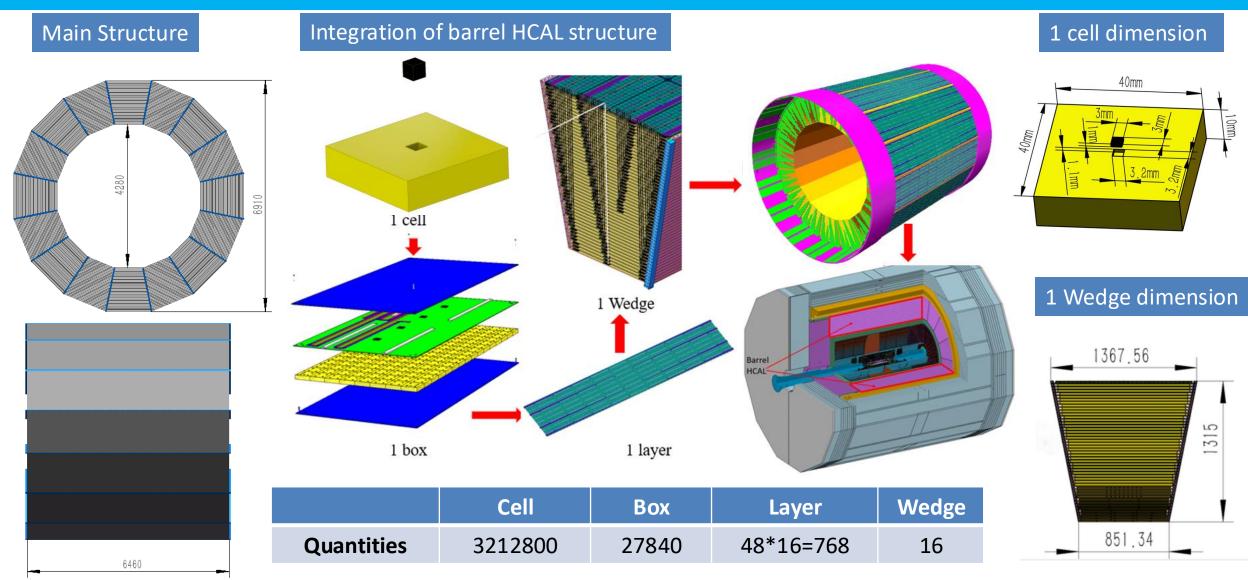
- Thickness of the Barrel : 1315 mm
- \circ Inner radius of the Barrel : 2140mm (D_{in}=4280 mm)
- Barrel Length along beam direction : 6460 mm
- Number of Layers : 48 (6 λ_1)



367 56

S 3

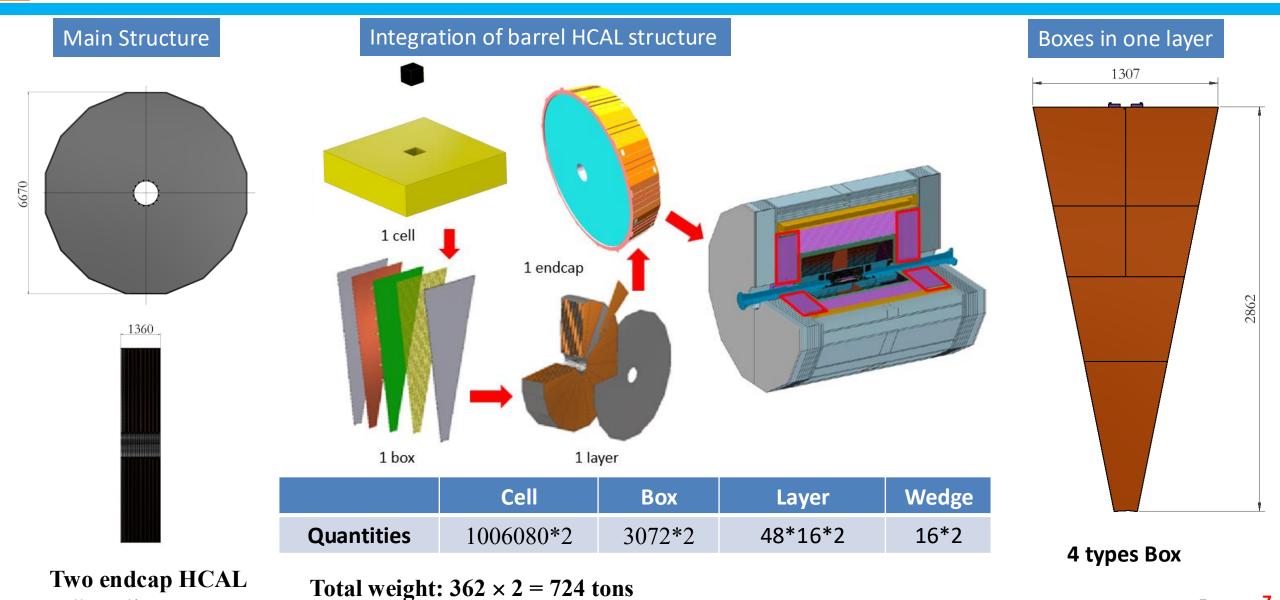
Barrel HCAL Mechanics



Length: 6460mm

Total weight: 955 tons CEPC WS EU 2025, Barcelona, 16-19 June 2025

Endcap HCAL Mechanics



CEPC WS EU 2025, Barcelona, 16-19 June 2025

Hengne Li

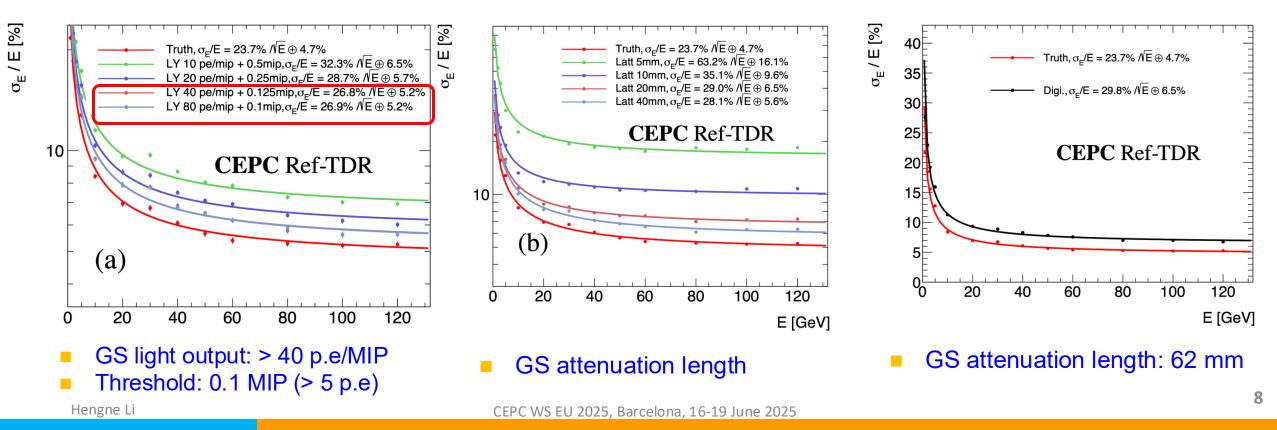
7

7

GS-HCAL Energy Resolution

A full detector geometry constructed with DD4hep in CEPCSW

- GS density 6 g/cm^3 , $\lambda_I = 242.8$ mm, attenuation length ~ 62 mm
- GS cell size $4 \times 4 \times 1$ cm³, 48 layers, $6\lambda_I$ in total
- Geometry: follow the mechanics design with supporting structures.
- Light output: LO ~ 60 p.e./MIP can satisfy the design goal.



 $\sigma_{\rm F}/{\rm E} = 29.8\%/\sqrt{E} \oplus 6.5\%$

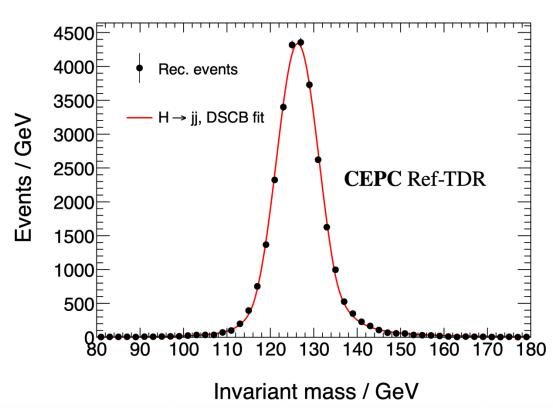
GS-HCAL Physics Performance

Hadron Energy Resolution (full simu. + digitization):

- MC Sample: $ee \rightarrow ZH \rightarrow \nu\nu gg$ @ 240GeV
- Tracker (Si + TPC) + Crystal ECAL + GS-HCAL, Cyber PFA Reconstruction

♦ BMR (H→gg) = 3.88%

Fitted Higgs mass is 126.32 \pm 0.04 GeV, σ (mjj) = 4.90 \pm 0.04 GeV.

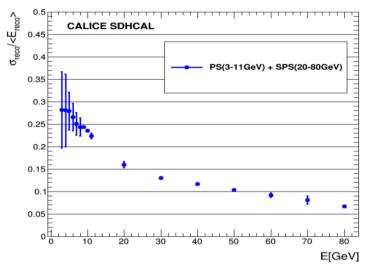


Performance Comparison

RPC-SDHCAL, 48-layer, 1x1 cm²



Pion Beam

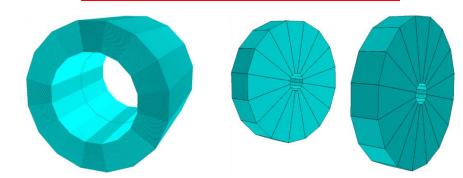




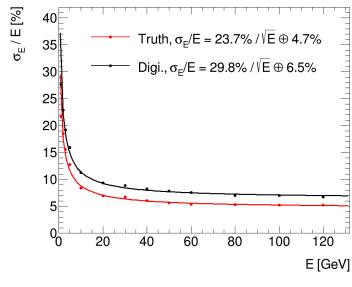
PS-HCAL, 40-layers, 4x4 cm²



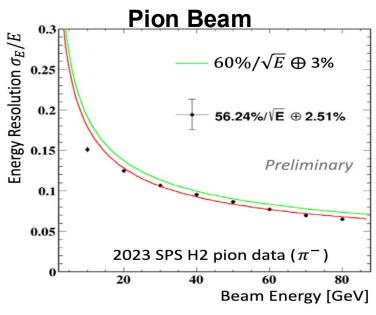
GS-HCAL, 48 layers, 4x4 cm²



MC Simulation



29.8% $/\sqrt{E} \oplus 6.5\%$



56. $2\%/\sqrt{E \oplus 2.5\%}$

CEPC WS EU 2025, Barcelona, 16-19 June 2025

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GS-HCAL Constant Term

> **PS-HCAL prototype**: 5λ , $\frac{\sigma_E}{E} = \frac{56.2\%}{\sqrt{E}} \oplus 2.5\%$, with shower Ξ/Ξ Ω 48 Layers 6λ GS HCAL start and end selection (require shower start at first 5 layers). 0.2 $\delta_{\rm E}/{\rm E} = 25.20\%/\sqrt{\rm E} \oplus 2.95\%$ > GS-HCAL in full sim+digi: 6λ , $\frac{\sigma_E}{F} = \frac{29.8\%}{\sqrt{F}} \oplus 6.5\%$ (all events) **CEPC** Ref-TDR 0.15 Low Energy 0.1 • All events at truth level: $\frac{\sigma_E}{E} = \frac{23.7\%}{\sqrt{E}} \bigoplus 4.7\%$ 0.05 10 • Shower starts at first 3 layers: $\frac{\sigma_E}{E} = \frac{25.9\%}{\sqrt{E}} \oplus 3.5\%$ H/H 0.25 • Low energy beam ($E_{\pi^-} < 30 \text{ GeV}$): $\frac{\sigma_E}{E} = \frac{25.2\%}{\sqrt{E}} \bigoplus 2.9\%$ 80 Layers 10λ GS HCAL $\delta_{\rm F}/{\rm E} = 25.54\% / \sqrt{{\rm E}} \oplus 2.94\%$ 0.2 • Large HCAL (80 layers, 10λ): $\frac{\sigma_E}{E} = \frac{24.7\%}{\sqrt{E}} \bigoplus 2.9\%$ **CEPC** Ref-TDR 0.15 80 layers (10λ) → Large constant term in GS-HCAL is partly due to 0.1 longitudinal leakage of the hadronic shower 0.05 50 Short attenuation length may also contribute CEPC WS EU 2025, Barcelona, 16-19 June 2025 Hengne Li

20

30

E [GeV]

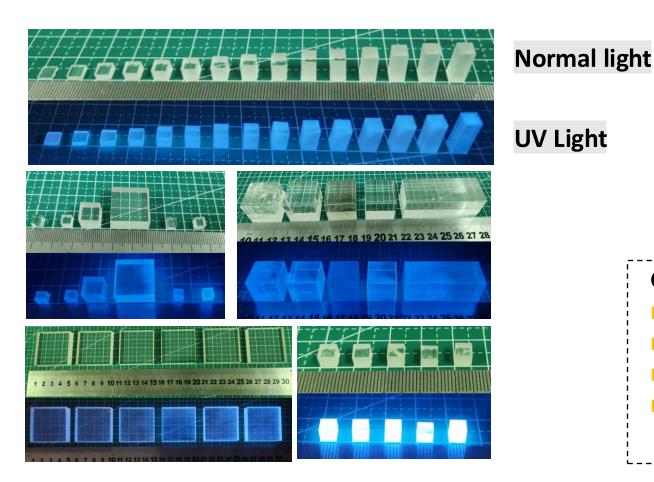
100

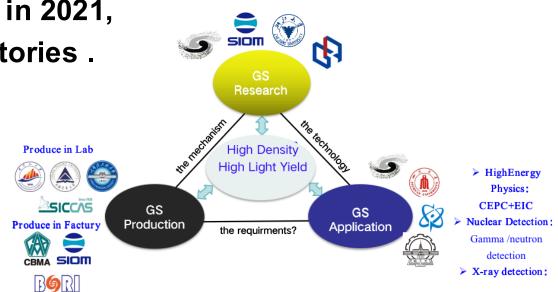
E [GeV]

11

GS Study

The GS collaboration was organized by IHEP in 2021, it includes 4 Institutes of CAS, 6 Univ., 3 Factories.

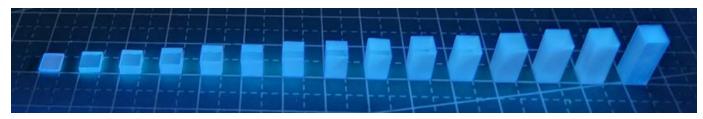




Gadolinium Fluoro-Oxide (GFO)
Density~6.0 g/cm³
LY ~ 1500 ph/MeV
Emission peak: 400 nm
Decay time: 60 and 500 ns

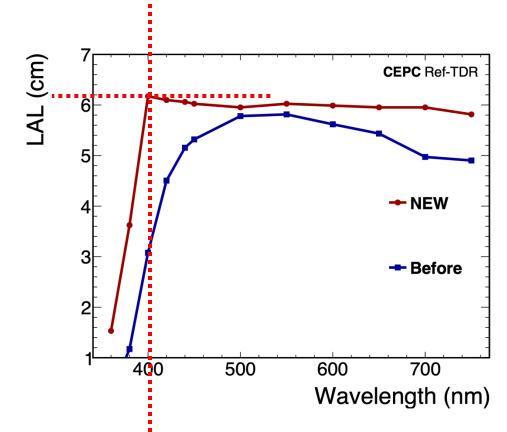
GS Study: Attenuation Length

- GFO samples with varying thicknesses were fabricated to measure the light attenuation length.
- Using energy spectra and light yield vs thickness of GFO to fit attenuation length: 6.2 cm @ 400nm

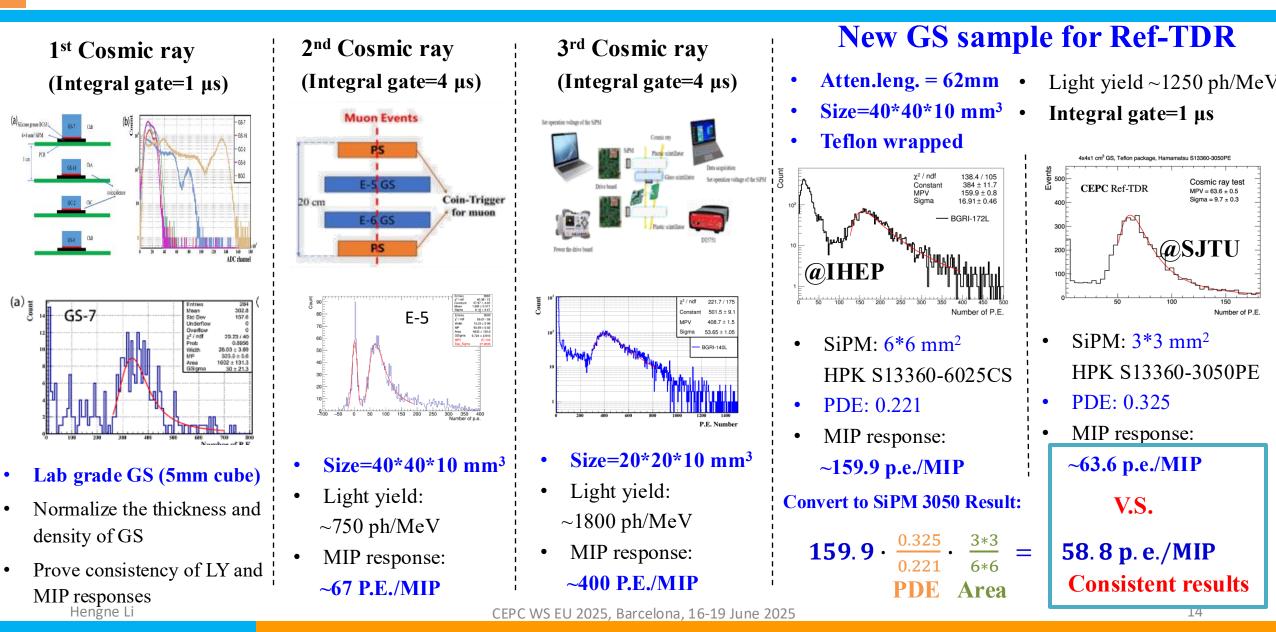


New GFO samples from three vendors are under test, promising results will be available soon.



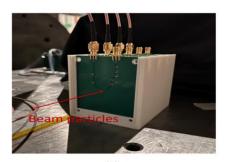


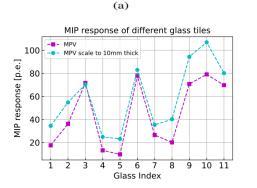
GS Study: cosmic ray tests



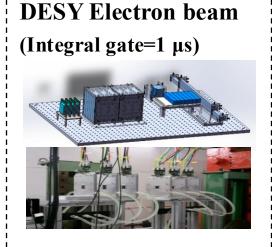
GS Study: beam tests

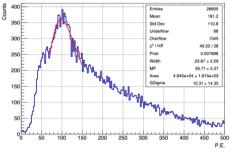
CERN Muon beam (Integral gate=1 μs)





- (25-40)*(25-35)*(4-10) mm³ •
- Typical light yield: 500-600 ph/MeV
- Typical MIP response: **60-100 P.E./MIP**





Size=40*40*10 mm³

- Typical light yield:600-700 ph/MeV
- Typical MIP response:
 80-90 P.E./MIP

New results from KEK, CERN, and DESY are coming soon.

Hengne Li

GS-HCAL Full-size Prototype (C3)

Preparation of full-size GS-HCAL prototype (2025-2026)

- ➤ Total: 48 layers
- > Each layer: 13×13 GS cells (52×52 cm²)
- $\blacktriangleright \text{ GS cell size: } 4 \times 4 \times 1 \text{ cm}^3$
- ➤ Total GS cells: 13 × 13 × 48 = 8112
- ➤ 1 SiPM (3×3 mm²) for each GS cell
- > 8112 NDL-SiPMs will be used
- ASIC Chip with power consumption of 15mW/ch
- Stainless steel as absorber and covers: 13.8mm

Cooperation with DRD4 and DRD6

- Sen Qian is deputy convener of WG4.1 in DRD4
- Contact person for GS-HCAL in WP6.1 in DRD6

TB plan (2027):

- > CERN: 2-180 GeV, e / μ / π beams
- CSNS (China): 1.6 GeV proton beam

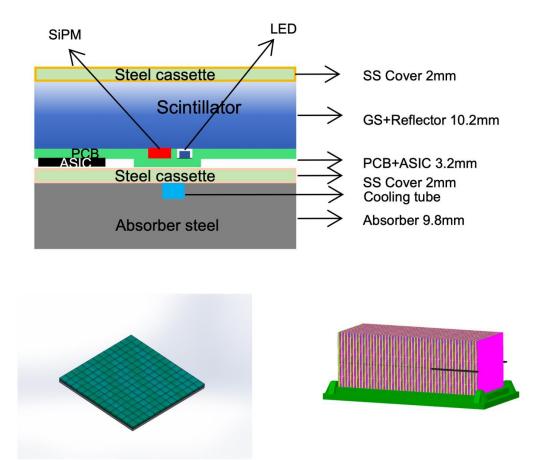


Figure 8.24: One layer and whole size of GS-HCAL prototype.

HCAL Research Group

- CEPC-HCAL team: IHEP, USTC, SJTU, XJTU, SCNU, SCU, HEU, ZZU
 - **Detector for PS/GS-HCAL:** Staff(9) + Student(5)
 - **Electronics:** Staff(5)
 - Mechanics: Staff(3)
 - **GS Collaboration:** 13 institutes, Staffs (26) + Students (10)

Convener: Sen Qian (IHEP), Jianbei Liu (USTC)

Physics: Manqi Ruan(IHEP), Haijun Yang (SJTU)

Software: Sengsen Sun(IHEP)

Design: Fangyi Guo(IHEP), Hengne Li(SCNU), Qingming Zhang(XJTU), Weizheng Song(IHEP), Peng Hu(261) Dejing Du(IHEP), Hongbing Diao(SUTC), Jiyuan Chen(SJTU), to design the GS-HCAL based on CEPCSW;
Glass Scintillator: Sen Qian(IHEP), Jing Ren(HEU), the GS collaboration (13 institutes, 26 staffs +10 students);
SiPM: Yuguang Xie(IHEP), Jifeng Han(SCU), Guang Luo(SYSU), SiPM and electronics for the GS performance test;
Electronics: Jingfan Chang(IHEP), to design the ASIC and FEE, power supply, cables etc.;
DAQ: Chen Boping(IHEP)
Mechanics and cooling system: Yatian Pei(IHEP), Junsong Zhang(IHEP), Shang Bofeng(ZZU)
Detector: Boxiang Yu(IHEP), Yunlong Zhang (USTC), Yong Liu (IHEP), GS-HCAL module, TB and cosmic test;

Summary and Future Plans

Physics requirement for the design:

- > Hadron energy resolution < $30\%/\sqrt{E}$
- Boson mass resolution (BMR) < 4%</p>
- GS-HCAL is selected as baseline based on its promising performance
 - Intensive R&D on high quality GS (e.g. light yield, decay time, attenuation length)
 - Update design of GS-HCAL mechanics, cooling and readout electronics
 - Simulation studies with CEPCSW demonstrated: with a Light output of 60 p.e./MIP and attenuation length of 62 mm, can well satisfy the physics requirement.

Future R&D plans

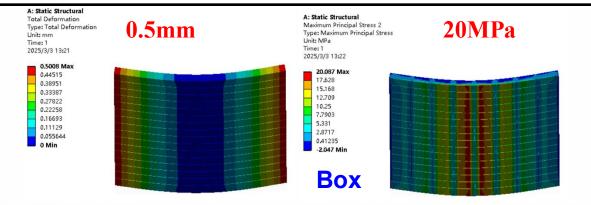
- > To develop techniques for mass production of GS, SiPM with low cost
- > To further optimize GS-SiPM coupling, cooling and readout electronics
- > To prepare full-size GS-HCAL prototype with integrated electronics for beam test

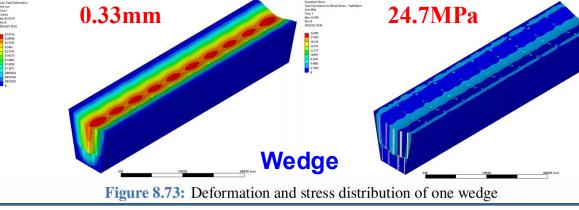


Thanks for your attention!

Mechanics

FEA simulation study to evaluate key parameters: deformation and stress

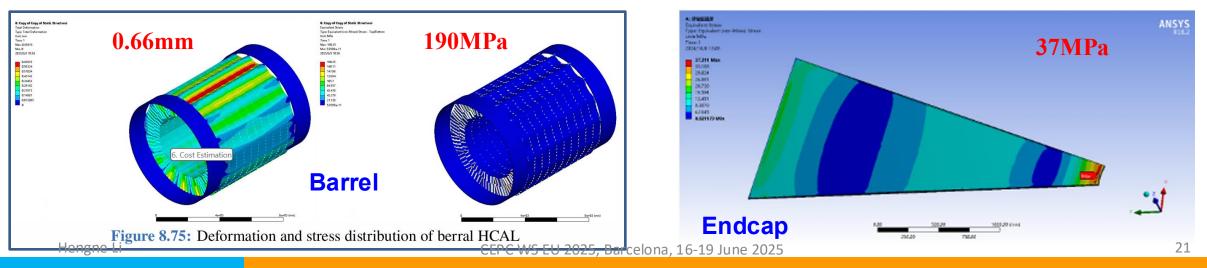




21

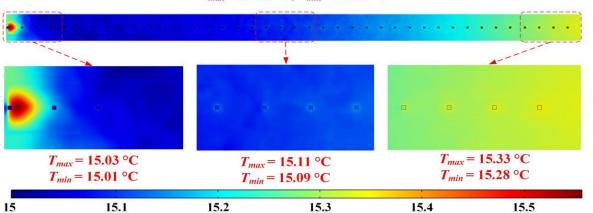
Figure 8.81: When the difference between the lowest point and highest point is 0.5mm (left), the stress distribution (right)

- Max deformation of GS box is 0.5mm, deformation of wedge is 0.33mm
- Max stress of GS is 20MPa (Box) and 37MPa (Endcap): less than allowable stress of GS (60MPa)



Cooling

Air cooling can not meet heat dissipation demands.
 Liquid cooling technology is employed to ensure efficient heat dissipation and temperature uniformity.



 $T_{max} = 15.56 \ ^{\circ}\text{C}, \ T_{min} = 15.00 \ ^{\circ}\text{C}$

FEA simulation of liquid cooling system

Inlet T=15 °C, flow rate 0.005 kg/s (inlet velocity 0.1 m/s).
 Temperature within same layer < 0.6 °C

◆ Temp. variations of chips in same module < 0.1 °C

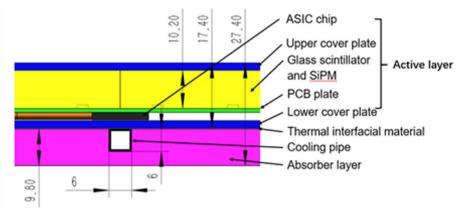
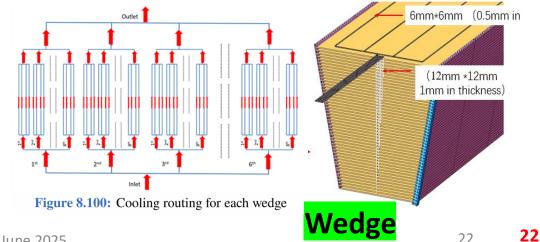


Figure 8.65: Cross section structure of each layer of detect module

- 4 pipes in each layer in parallel
- 8 layers gather in one pipe in parallel
- One end is inlet and another end is outlet

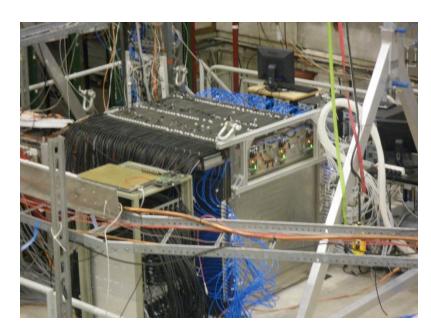


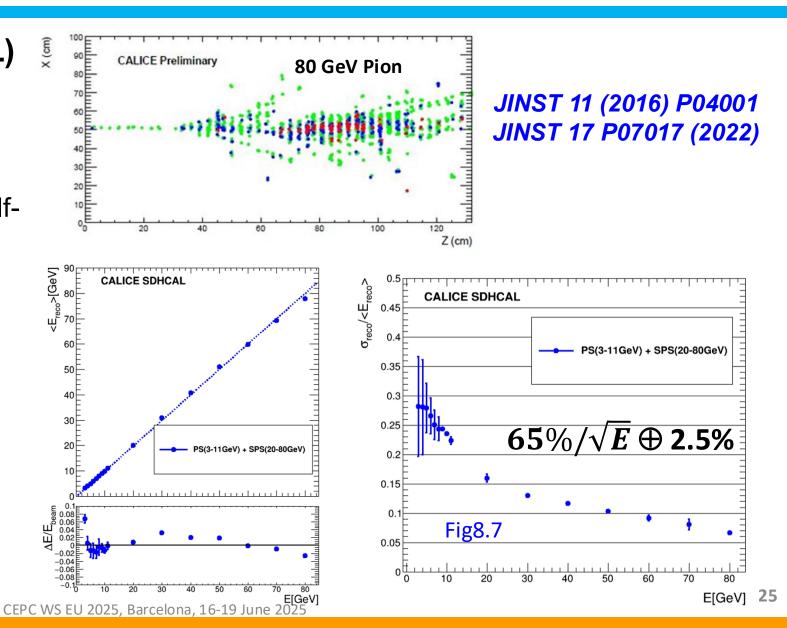
Hengne Li

2.1 RPC based SDHCAL (Prototype)

Semi-digital HCAL (SDHCAL)

- High granularity (1cm x1cm)
- 48 layers (1m x 1m x 1.3m)
- Three thresholds readout
- Stainless-steel absorber with selfsupporting mechanical structure

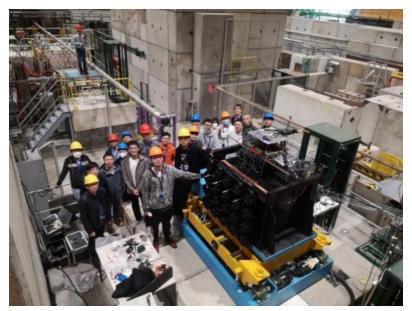


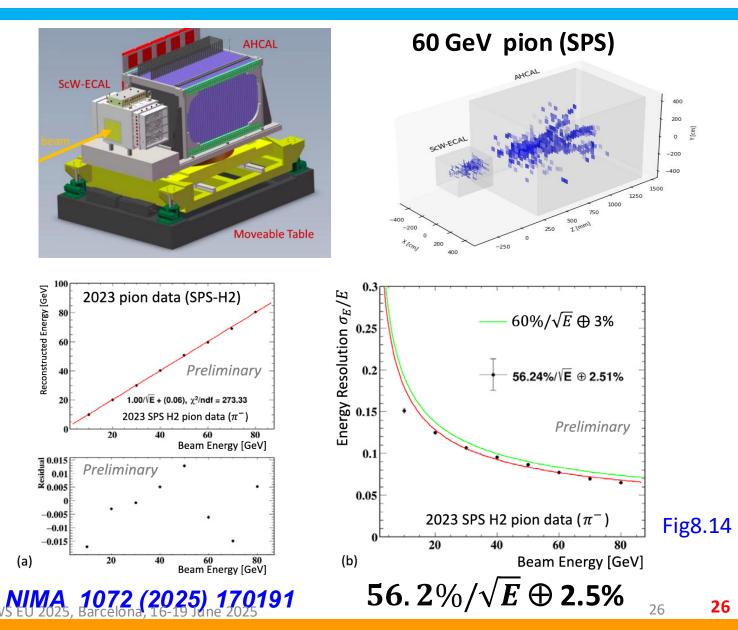


2.2 Plastic Scintillator HCAL (Prototype)

Plastic Scint. AHCAL (PSHCAL)

- High granularity (4cm x4cm)
- 40 layers (72 cm x 72cm x 1.1m)
- Plastic Scintillator + SiPM (12960)
- Stainless-steel absorber with selfsupporting mechanical structure



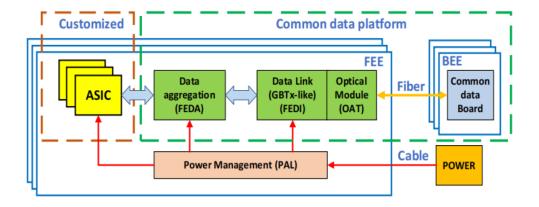


5.2 Readout Electronics (C2)

ASIC Optical Data Module aggregation Cable space Power Manager Power Data Data Power Data Data Power Data Data Manager Link aggregation Link Link Manager aggregation Manager aggregation Barrel end ASIC A 70 \succ FEE Cable direction Cable direction

Front-End Electronics (FEE) readout boards in HCAL cell Box

- Thickness: 3.2mm = PCB 1.2mm + ASIC Chip 2mm
- SiPMs, ASICs and Data Aggregation
- PCB dimensions: flexible in different positions
- SiPM-readout ASIC: under development
 - Self-developed for CEPC calorimeter system
 - Functionality: energy and time measurements
 - Power consumption: target at 15mW/ch
- Aggregation board at the end of barrel, cable connection



See Wei Wei's talk for details

- Energy Measurement: ASIC for ECAL & HCAL
- Data transmission: common data platform
- Trigger mode: FEE triggerless readout

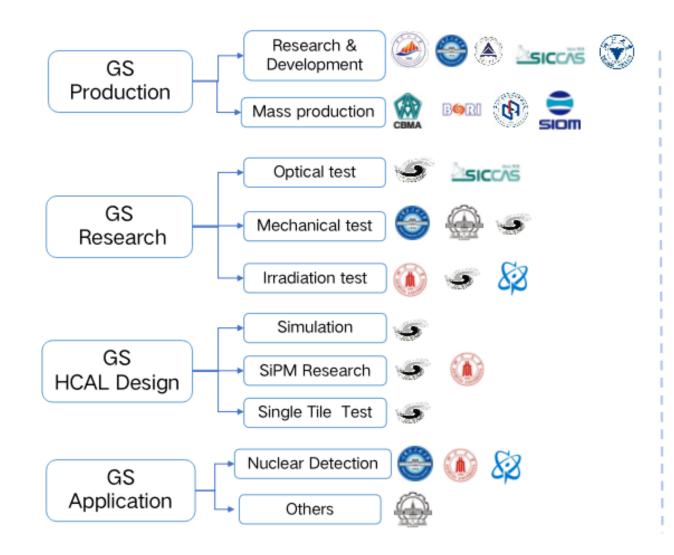
7.2 Research Team of GS-HCAL

- ➢ GS collaboration: 13 institutes, 26 faculty/staff, ~10 students
- > HCAL working group: 8 institutes, 17 faculty/staff, ~10 students



Hengne Li

Research Team of GS





Institute of High Energy Physics, CAS 中国科学院高能物理研究所

Jinggangshan University 井冈山大学

Beijing Glass Research Institute 北京玻璃研究院

China Building Materials Academy 中国建筑材料研究院

China Jiliang University 中国计量大学

Harbin Engineering University 哈尔滨工程大学

Harbin Institute of Technology 哈尔滨工业大学

Sichuan University 四川大学

Shanghai Institute of Ceramics, CAS 中国科学院上海硅酸盐研究所

Shanghai Institute of Optics and Fine Mechanics, 中国科学院上海光学精密机械研究所

CNNC Beijing Nuclear Instrument Co., 中核(北京)核仪器有限责任公司

Zhejiang University 浙江大学

Ganjiang Innovation Academy, CAS 中国科学院積江創新研究院

GS-HCAL Digitization Model

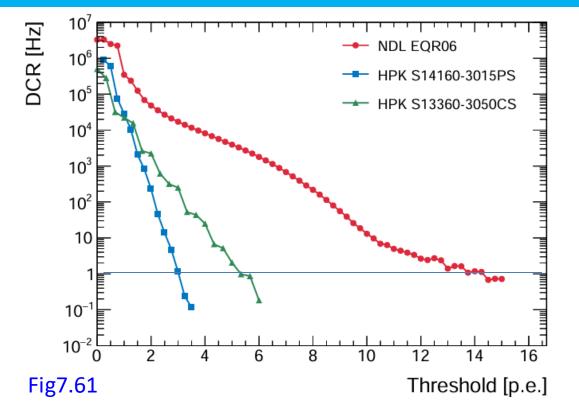
8.9.2.1 Energy linearity and resolution

The energy linearity and resolution are estimated with Geant4 simulation in CEPCSW. In order to study the intrinsic energy response in GS-HCAL, all inner sub-detectors are removed. A digitization model is constructed considering the following items:

- Birks constant. Currently a preliminary estimation of $C_{Birks} = 0.01$ is applied, considering the BGO has $C_{Birks} = 0.0086$. A measurement with heavy ion beam is being planned.
- Light yield. With the measurement from glass scintillator samples, the intrinsic MIP light yield can reach to 2000 ph/MeV, thus the detected light yield is expected to be at least 100 p.e./MIP. This satisfies the requirement from noise and 0.1 MIP threshold.
- Attenuation length. 2.3 cm attenuation length is expected, based on current measurements. While more detailed studies of the glass scintillation properties need to be studied.
- Threshold. With the scanned impact on energy resolution, a 0.1 MIP threshold is expected.
- SiPM response.
- Electronic system.
- Other items are considered as negligible after the calibration.

This model gives an estimation of the energy resolution $\sigma_E/E = 29.8\%/\sqrt{E} \oplus 6.5\%$ and linearity within 2% before calibration in Figure 8.106 The physics list '*QGSP-BERT*' is used as default one. Other physics lists are also tested. The large constant term is contributed with the longitudinal leakage from this $6 \lambda_I$ design, which is limited by the total detector volume and cost. This result is better than the traditional HCAL with typical energy resolution of $\sigma_E/E = 60\%/\sqrt{E} \oplus 3\%$. Hengne Li CEPC WS EU 2025, Barcelona, 16-19 June 2025

SiPM Dark Current Rate (DCR)



- ➢ HPK 13160: DCR ~ 0.5MHz,
- Threshold >5 pe (0.1 MIP), DCR rate ~ 1Hz
- ➢ integral time ~1us,
- \rightarrow SiPM noise rate ~ 5.3M*10⁻⁶ ~ 5.3

The nominal dark count rate (DCR) of SiPMs, along with their testing temperature and bias voltage.

SiPM	DCR (MHz)	Over votage (V)	Temperature ($^{\circ}C$)
HPK \$13360-3050CS	0.5	3	25
HPK S14160-3015PS	0.7	4	25
NDL EQR06 11-3030D-S	2.5	8	20

MPPC (multi-pixel photon counter)

S13360 series

Electrical and optical characteristics (Typ. Ta=25 °C, unless otherwise noted)

					Dark o	count*5						
Type no.	Measurement conditions	Spectral response range λ	Peak sensitivity wavelength λp	Photon detection efficiency PDE ^{*4} $\lambda = \lambda p$	Тур.	Max.	Terminal capacitance Ct	Gain M	Breakdown voltage VBR	Crosstalk probability	Recommended operating voltage Vop	Temperature coefficient at recommended operating voltage ∆TVop
		(nm)	(nm)	(%)	(kcps)	(kcps)	(pF)		(V)	(%)	(V)	(mV/°C)
S13360-1325PE		320 to 900			70	210	60					
S13360-3025CS	Versen	270 to 900			400	1200	320					
S13360-3025PE	Vover =5 V	320 to 900]	25	400	1200	520	7.0 × 10 ⁵		1	VBR + 5	
S13360-6025CS	5.	270 to 900			1600	5000	1280					
S13360-6025PE		320 to 900			1000	5000	1200					
S13360-1350PE		320 to 900]		90	270	60		53 ± 5 3		Vbr + 3	54
S13360-3050CS		270 to 900]		500	1500	320			3		
S13360-3050PE	Vover =3 V	320 to 900	450	40	500	1500	320	1.7×10^{6}				
S13360-6050CS		270 to 900]		2000	6000	1200	1				
S13360-6050PE	1	320 to 900]		2000	6000	1280					
S13360-1375PE		320 to 900	1		90	270	60		1			
S13360-3075CS	Vover =3 V	270 to 900	1		500	1500	220	1				
S13360-3075PE		320 to 900	1	50	500	1500	320	4.0×10^{6}		7	VBR + 3	
S13360-6075CS	-5 V	270 to 900			2000	6000	1200]				
S13360-6075PE		320 to 900	1		2000	6000	1280					

*4: Photon detection efficiency does not include crosstalk or afterpulses.

*5: Threshold=0.5 p.e.

Note: The above characteristics were measured at the operating voltage that yields the listed gain. (See the data attached to each product.)

Hengne Li

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GS+SiPM

NDL EQR20



HPK S13360-3025CS

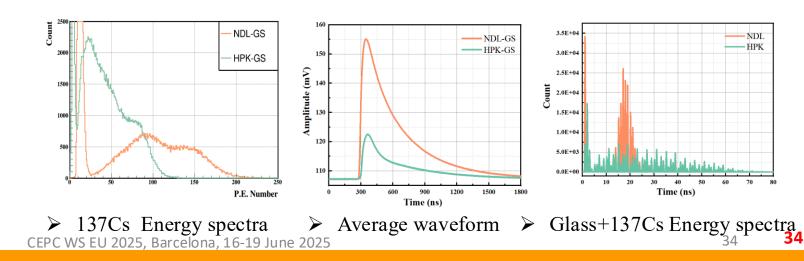
	NDL	HPK
Photosensitive area (mm)	3×3	3×3
Operation Voltage (V)	32.3	56.64
Gain	8×10^{5}	7×10^{5}
SPE channel	99	61
PDE @390nm (%)	42	22
P.E. Number	138	75
Energy resolution (%@662keV)	40.9	44.2
Scintillation decay (ns) Hengne Li	487.6	594.4

Mass production of high quality SiPM;

- HPK S13360 series (3x3 mm²) ~ 20% Detection efficiency.
- HPK S14160 series have about 43% PDE @390nm, more suitable for HCAL, will be tested soon.
- NDL $(3x3 \text{ mm}^2) \sim 40\% \text{ DE}$, could be improved to 60% in the future
- IHEP will cooperation with NDL for the performance test

• Mass production of low cost SiPM;

- Hamamatsu HPK / NDL SiPM (3x3 mm²) ~ \$1.5/ch with O(5M) pieces
- Optimizing granularity, GS and SiPM couplings to reduce cost

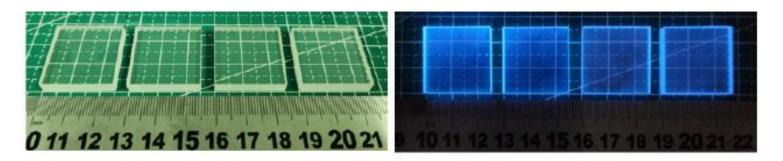


SiPM+GS Coupling

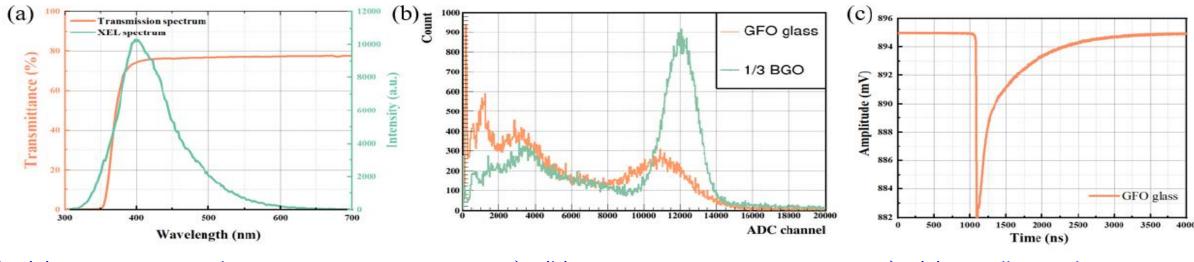
C:DM compled glass	Relative detec	ction efficiency	Glass	Glass	SiPM LED		SiPM LED
SiPM coupled glass	TiO ₂	Teflon		3×3 SiPM	Cassette cover	➢ SS Cover 2mm	Steel cassette
Reflectivity (%@400 nm)	~70	~86	6×6 SiPM		Scintillator		Scintillator
Single 3×3 mm	0.7	/	Glass	Glass		✓ GS+Reflector 10.2mm	
Single 6×6 mm	1	1.43	Class		Cassette cover	PCB+ASIC 3.2mm SS Cover 2mm	Steel cassette
Four 3×3 mm	2.08	2.4	□ 3×3 SiPM	3×3 SiPM	Absorber stainless steel	Absorber 9.8mm	Absorber steel
Four 6×6 mm	2.98	4.2	5 × 5 50 M			Absorber 9.omm	

- > Because the light attenuation length is only ~23 mm, more SiPMs are needed to collect sufficient light.
- > One scintillator is coupled with either 1, 2, or 4 SiPMs (3 mm \times 3 mm SiPMs).
- In the future, the performance of GS is expected to improve, potentially allowing the use of fewer SiPMs possibly even just one.
- Glass scintillators bonded to the PCB with optical glue were tested. The results show that the glue is sufficiently strong for this purpose.
- There is a gap to hold the SiPM either in the GS or in the PCB. More tests are needed to determine the optimal position of this gap (in the glass or PCB) and to identify a low-cost and practical method for implementation.

5.1 GS Study: large size (4×4×1cm³)



- Density=6.0 g/cm³
- LY=1506 ph/MeV
- ER=41.2%
- LO in 1µs=1129 (75%)
- Decay=53 (3%), 655 ns
- > Three company/institutes are capable to produce larger size GS with mass production;
- > For GS-HCAL prototype: Size = $40*40*10 \text{ mm}^3$; Density = 6.0 g/cm³;
- Light yield could > 1000 ph/MeV, but typical decay time > 100 ns;



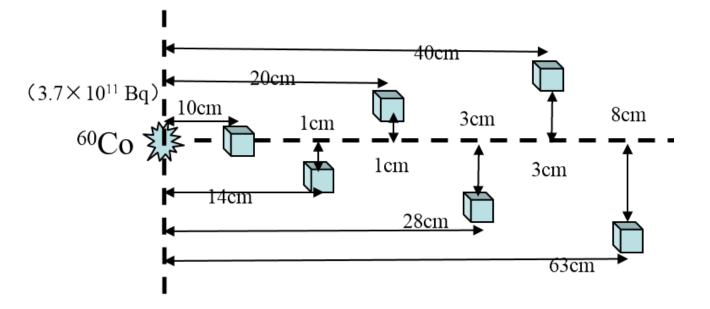
(a) Transmission and XEL spectra

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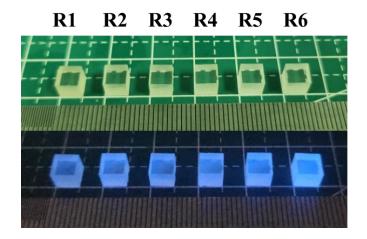
(c) Scintillation decay curves 41

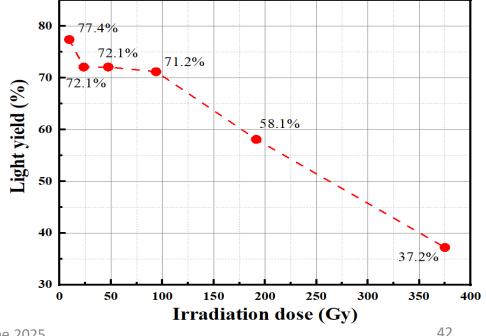
5.1 GS Study: Irradiation Test

 □ 6 GS samples (5×5×5 mm³) were irradiated with a ⁶⁰Co source of 3.656×10¹¹ Bq
 □ GS samples were placed with different distances

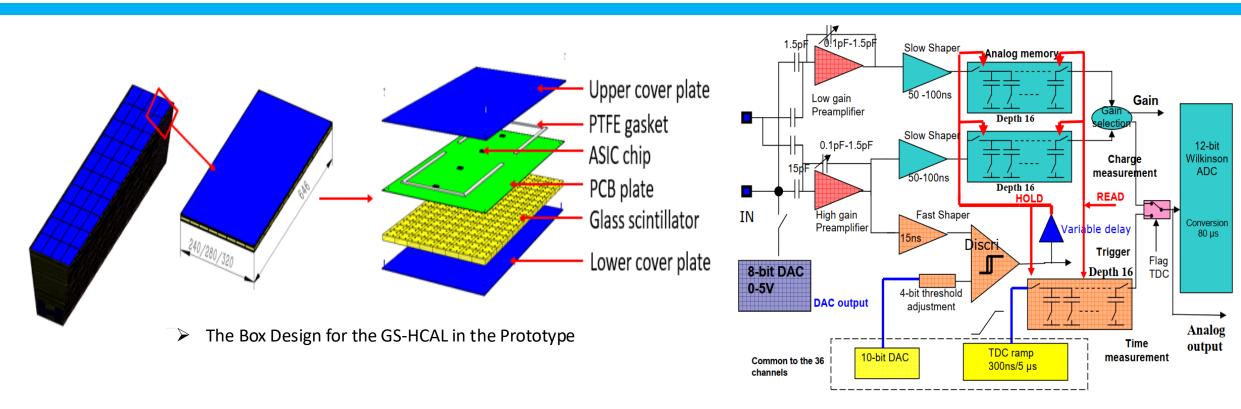


□ Light output of GS samples are reduced to 58% of its original level after ~200 Gy dose exposure which is consistent with proton irradiation in 20 years (~200 Gy)



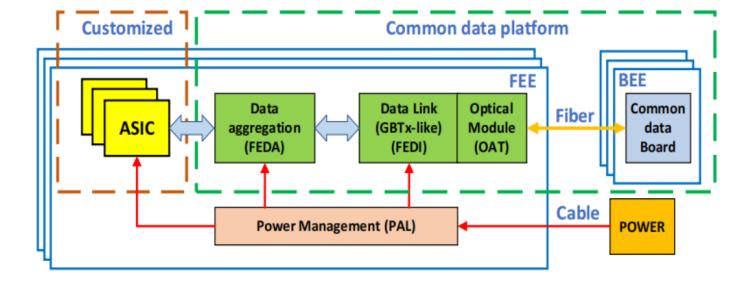


Power Supply for SiPM



- SiPMs in the GS-AHCAL receive a uniform bias voltage via a PCB box.
- SiPMs will be categorized, and those with similar operating voltages will be grouped in one box, sharing the same power supply.
- ASIC chip can regulate the bias voltage within ±0.5 V, which is narrower than the ±5 V range of SPIROC2E.
 Tests have confirmed that ±0.5 V regulation is sufficient for SiPM operation.
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- Dynamic range of charge measurement:
 - 0.1MIPs (800fC) 100MIPs (800 pC);
- Charge resolution: 10% at 1 MIP;
- Integral non-linearity (INL): < 1%
- SiPM Terminal Capacitance : **<100pF**;
- Single channel average event rate : 1.5kHz/ch at Higgs;
- Single channel maximum event rate :
 - 42.33kHz at Higgs.



- Energy Measurement: ASIC for ECAL & HCAL
- Data transmission: common data platform
- Trigger mode: FEE triggerless readout

5.3 GS-HCAL Full-size Prototype (C3)

		2021-2023	2024-2025	2026	2027	
	Physics+ Software+ Design+ Mechanics	Design TDR	Optimization calibration	new Design; calibration; beam test	Gass 10mm Steel	
	Glass Scintillator	R&D 5X5X5 mm ³	R&D 40X40X10 mm ³	10K pieces mass production batch test	Assembly the cell;	
L L LOMM T T J	SiPM	test samples	performance test, choice	40K pieces batch test	Finish the Module for performance test;	
	Electronics	the design of ASIC and FEE, power supply	V1,V2 performance test	V2 mass production batch test	the cosmic ray test; the beam test;	

Working Plan

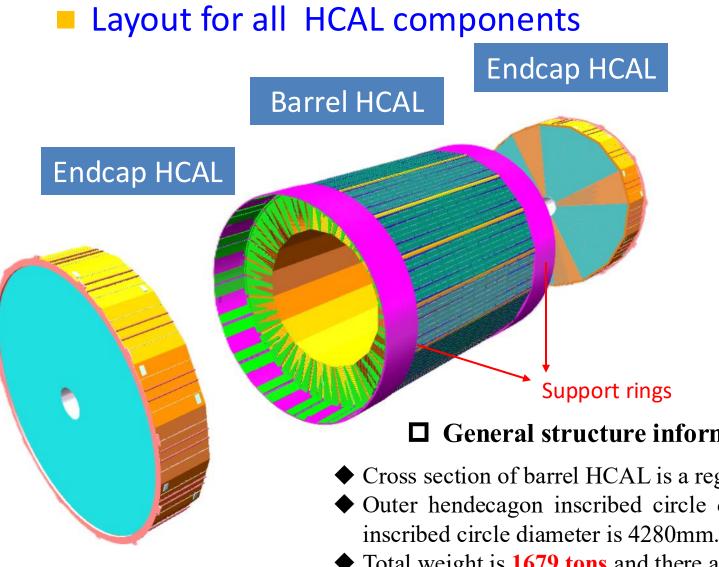
- Plan of the Prototype of GS-HCAL in the next two years (2025-2026).
- Prototype of the HCAL was designed right now.

					2025年 2026年	Prototype design
ID	Item	Start time	Compeleted	Duration	01月 02月 03月 04月 05月 06月 05月 06月 07月 08月 09月 10月 11月 12月 01月 02月 03月 04月 05月 06月 07月 08月 09月 10月 11月 12月	
1	GS tiles production	1/1/2025	30/3/2026	64.8周	·	
2	GS and R&D	1/1/2025	30/6/2025	25.8周		
3	GS mass production and QC	1/7/2025	30/3/2026	39周		
4	SiPM purchase and QC	1/1/2025	1/1/2025	0周		
5	SiPM selection	1/1/2025	30/6/2025	25.8周		
6	SiPM purchase and QC	1/7/2025	31/3/2026	39.2周		
7	ASIC chips research and production	1/1/2025	30/3/2026	64.8周	×	
8	ASIC chips design	1/1/2025	30/9/2025	39周		
9	ASIC chips production	1/10/2025	30/3/2026	25.8周		
10	Electronics design and production	1/10/2025	1/7/2026	39.2周	7	
11	PCB design	1/10/2025	27/2/2026	21.6周		
12	PCB production	2/3/2026	1/7/2026	17.6周		
13	Machine and cooling	1/1/2025	1/7/2026	78.2周		
14	Machine and cooling design	1/1/2025	30/9/2025	39周		
15	Machine and cooling installation	1/10/2025	1/7/2026	39.2周		Total: 18 lavers
16	Integration of Sensitive Layers and test	1/1/2026	30/9/2026	39周		 Total: 48 layers
17	GS-prototype integration and test	1/7/2026	30/11/2027	74周		Each layer: 13*13 glasses

- This study is to address the IDRC **Comment ③**:
- Preparation and beam testing of full-size HCal prototype;

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HCAL Mechanics Design



D Requirements:

- Support structure zone is as lower as possible.
- Maximum stress of different materials need to be lower than their allowable stress level.
- Deformation of different materials need to be controlled so that there will be no broken parts under different conditions.
- Outer contour dimension tolerance need to be 0mm to -5mm;
- Inner contour dimension tolerance need to be 0mm to +5mm.

General structure information:

- Cross section of barrel HCAL is a regular hendecagon
- Outer hendecagon inscribed circle diameter is 6910mm and the inner hendecagon inscribed circle diameter is 4280mm.
- Total weight is 1679 tons and there are totally 5224960 (~530M) glass scintillator CEPC WS EU 2025, Barcelona, 16-19 June 2025

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2.1 RPC-DHCAL (Gas Detector)

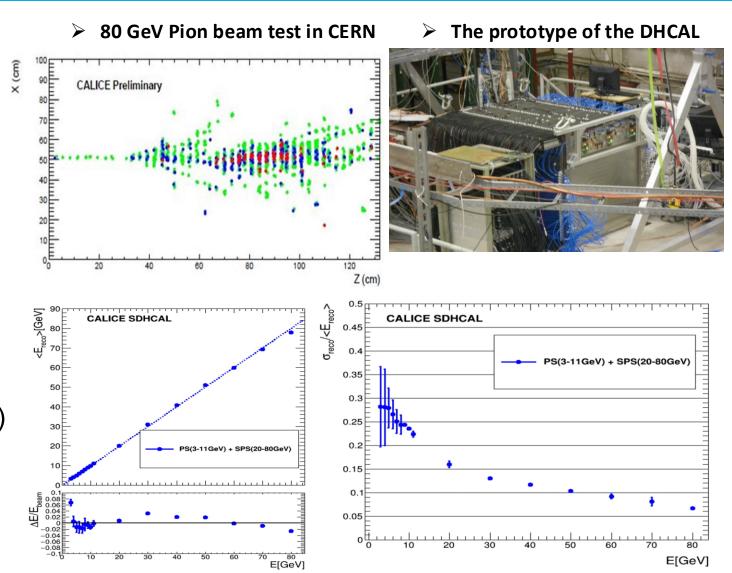
Semi-digital HCAL (SDHCAL)

- High granularity (1cm x1cm)
- 48 layers (1m x 1m x 1.3m)
- Three thresholds readout
- Stainless-steel absorber with selfsupporting mechanical structure

DHCAL performance:

- Higgs boson mass resolution(BMR):
- $H \rightarrow gg$: 3.68% (full sim + Arbor rec.)
- Energy Linearity within \pm 1.5%?
- Energy Resolution:





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2.2 PS-HCAL

■ Plastic Scintillator-AHCAL (PSHCAL)

- High granularity (4cm x4cm)
- 40 layers Three thresholds readout
- Plastic Scintillator + SiPM
- Stainless-steel absorber with selfsupporting mechanical structure

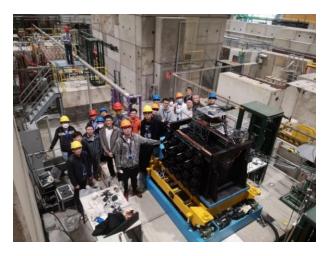
■ PS-HCAL performance:

- Higgs Boson Mass Resolution (BMR):
- $H \rightarrow gg$: 3.77% (full sim + Arbor rec.)
- Energy Linearity within \pm 1.5%
- Energy Resolution:

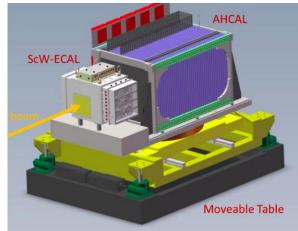
Hengne Li

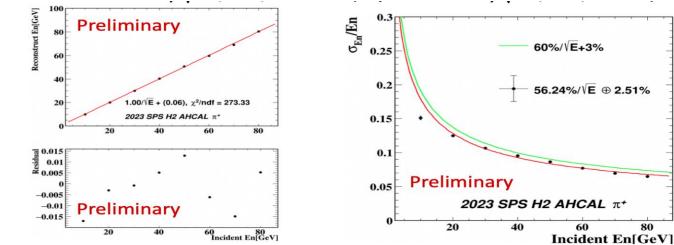


80 GeV Pion beam test in CERN



> The prototype of the DHCAL





CEPC WS EU 2025, Barcelona, 16-19 June 2025 JINST 17 (2022) P05006

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2.2 Plastic Scintillator HCAL (Prototype)

■ We have developed a PS-HCAL prototype and TB at CERN in 2022-2023

Calo	Layers	material	Absorber	Granularity	Electronics	Thickness	Resolution	Weight
PS-HCAL	40	PS+SiPM \$14160-1315	Fe	$4 \times 4 \text{ cm}^2$	SPIROC-2E 12960-ch	4.6 λ _I	60%/√ <i>E</i> ⊕ 3%	5.0 T



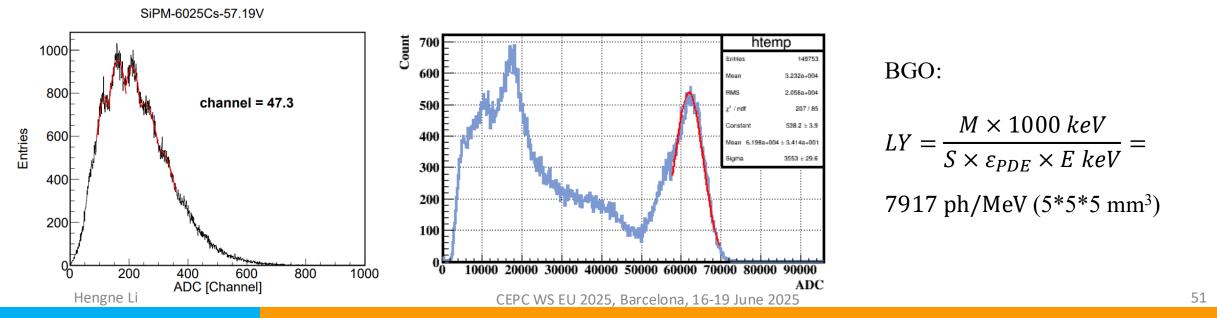
Light Yield

• Light yield/ Light output:

The efficiency of converting particle deposition energy into photons; photons/MeV, requires the device to be able to distinguish a single photoelectron signal. The results are obtained by comparing a single photoelectron signal with a test sample to the full-energy peak.

• Intrinsic light yield:

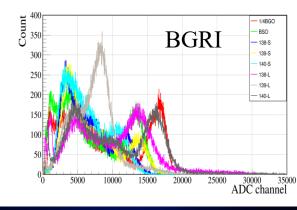
The light yield without any light loss inside the scintillator.

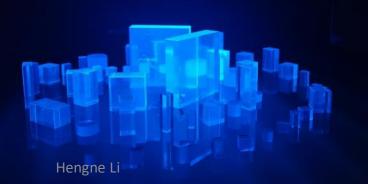


Progress of large size GS

BGRI

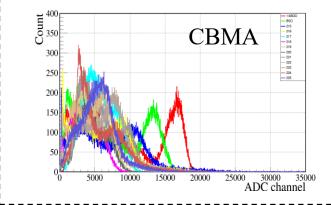
- Size=40*40*10 mm³
- Density=6.0 g/cm³
- LY=1506 ph/MeV
- ER=41.2%
- **LO in 1\mus=1129 (75%)**
- Decay=53 (3%), 655 ns

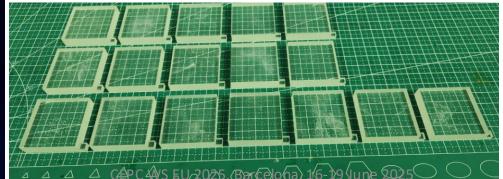


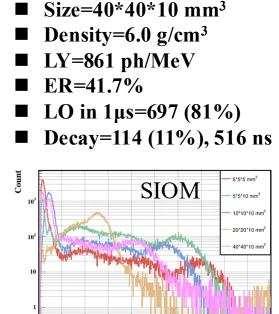


CBMA

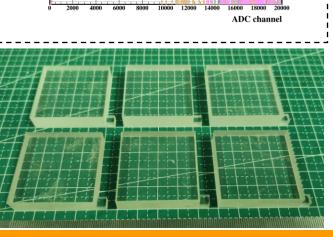
- Size=40*40*10 mm³
- **Density=6.0** g/cm^3
- LY=1119 ph/MeV
- ER=57.1%
- LO in 1μ s=616 (55%)
- Decay=80 (4%), 1167 ns



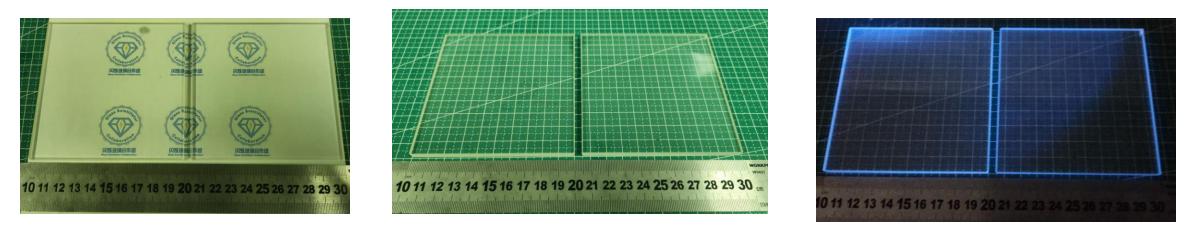


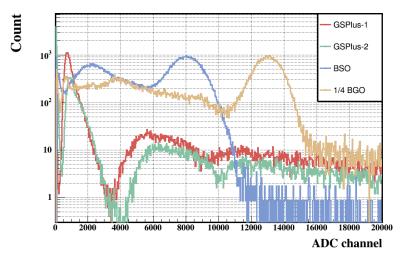


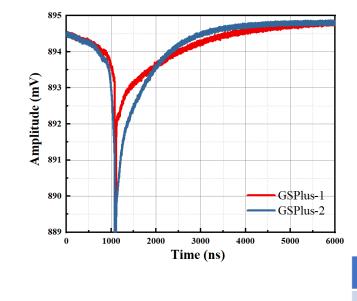
SIOM



Ultra-Large GS (10cm X 10cm)



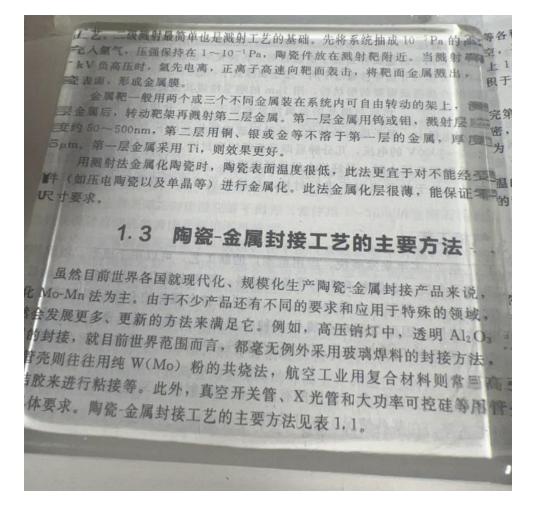


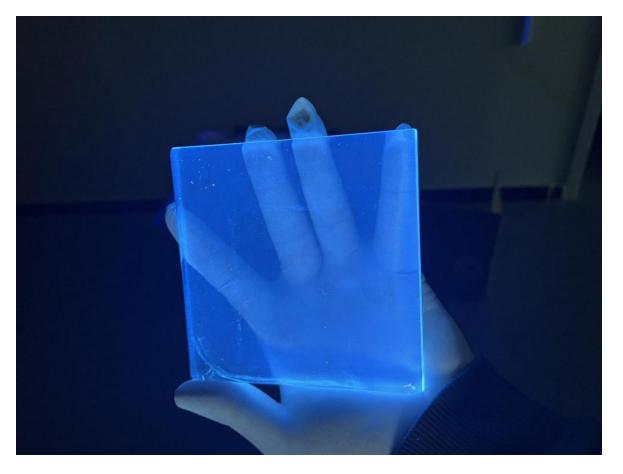


	LY (ph/MeV)	Decay time (ns)
GSPlus-1	732	101.9 (1.0%), 1456.5
GSPlus-2	795	72.1 (3.3%), 783.0

	5*5*5 mm ³	5*5*10 mm ³	10*10*10 mm ³	20*20*10 mm ³	40*40*10 mm ³
LY from PMT (ph/MeV)	1464	1273	1155	941	861

Ultra-Large GS (12.5cm X 122cm)





Scintillator-AHCAL: Materials



Plastic Scintillator

Glass Scintillator



Crystal Scintillator

Large density	\star
High light yield	
Energy resolution	
Low cost	
Fast decay	
Large size	

★ ★ ★ ★ ★

Large density $\bigstar \bigstar$ High light yield $\bigstar \bigstar$ Energy resolution $\bigstar \bigstar$ Low cost $\bigstar \bigstar$ Fast decay $\bigstar \bigstar$ Large size $\bigstar \bigstar$

Large density	$\star\star$
High light yield	
Energy resolution	
Low cost	
Fast decay	
Large size	